



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC0805NLS	Issued	23. June 2021
MA#	MA005432736		
Package	PG-TDSON-8-50	Weight*	106.40 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.706	0.66	0.66	6639	6639
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		128	
	non noble metal	zinc	7440-66-6	0.055	0.05		512	
	non noble metal	iron	7439-89-6	1.090	1.02		10247	
	non noble metal	copper	7440-50-8	44.271	41.62	42.70	416078	426965
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	408	408
encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		800	
	plastics	epoxy resin	-	3.918	3.68		36819	
	inorganic material	silicondioxide	60676-86-0	38.580	36.26	40.02	362588	400207
leadfinish	non noble metal	tin	7440-31-5	1.264	1.19	1.19	11877	11877
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	273	273
solder	noble metal	silver	7440-22-4	0.026	0.02		241	
	non noble metal	tin	7440-31-5	0.051	0.05		482	
	non noble metal	lead	7439-92-1	0.949	0.89	0.96	8919	9642
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	zinc	7440-66-6	0.018	0.02		173	
	non noble metal	iron	7439-89-6	0.368	0.35		3456	
	non noble metal	copper	7440-50-8	14.930	14.03	14.40	140317	143989
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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